#### Page 2.

#### **EAST Search History**

# Ref	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
SI	704	451/56.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	SR S	OFF	2004/09/22 10:37
23	478	451/60.cds.	US-PGPUB; USPAT; EPO; JPO; DERWENT	æ	0FF	2004/09/22 10:37
ß	254722	polish\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT	క	OFF	2004/09/22 10:38
\$	2208	451/41.ccts. and polish\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT	ĕ	OFF	2004/09/22 10:38
SS	480	451/56.ccts. and polish\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT	8	OFF	2004/09/22 10:38
አ	380	451/60.ccls. and polish\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT	8	OFF	2004/09/22 10:39
2S	419839	ped	US-PGPUB; USPAT; EPO; JPO; DERWENT	SO.	OFF	2004/09/22 10:39
88	94	"3-hydroxy 4-pyrones"	US-PGPUB; USPAT; EPO; JPO; DERWENT	R	PF0	2004/09/22 13:04
SS	955901	("3-hydroxy-4-pyrones") or (hydroxy adj1 butyrolactones) or borane borohydrides (dialkylamine adj boranes) formaldehyde (formic adj acid) hydrogen hydroquinones hydroxylamine (hypophosphrous adj acid) trihydroxybenzene (solvated adj electrons) (sulfurous adj acid)	US-PGPUB; USPAT; EPO; JPO; DERWENT	& ·	OFF	2004/09/22 13:15

#### **EAST Search History**

017	055001	("3-hydroxy-4-rymones") or	IIC.OCOLIB.	8	1 2	71-51 56/00/1900
270	7000	(hydroxy adj) butyrolactones) or borane or bordhydrides or dialkylamine adj boranes) or formaldehyde or (formic adj acid) or hydrogen or hydroquinones or hydroxylamine or (hypophosphorous adj acid) or trihydroxybenzene or (solvated adj electrons) or (sulfurous adj acid)	USPAT; EPO; JPO; DERWENT	5	5	77.60,460
S11	303143	("428" or "156" or "51").das.	US-PGPUB; USPAT; EPO; JPO; DERWENT	8	OFF	2004/09/22 13:18
512	43264	("3-hydroxy-4-pyrones") or (hydroxy adj1 butyrolactones) or boxane borohydrides (daikylamine adj boranes) formaldehyde (formic adj acid) hydrogan hydroquinones hydroxylamine (hypophosphorous adj acid) thihydroxylenzene (solvated adj electrons) (sulfurous adj acid) ) and (("428" or "156" or "51").cds.)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ĕ	FIO.	2004/09/22 13:18
S13	0	"451.cdas"	US-PGPUB; USPAT; EPO; JPO; DERWENT	æ	OFF	2004/09/22 13:18
S14	64433	"451".clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT	æ	OFF	2004/09/22 13:18
\$15	1097	(("3-hydroxy-4-pyrones") or (hydroxy adj.1 butyrolactones) or borane boronydrides (dialkylamine adj boranes) formaldehyde (formic adj acid) hydrogen hydroquinones hydroxylamine (hypophosphorous adj acid) hydroxylenzene (sohvated adj electrons) (sulfurous adj acid) ) and "451".clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT	Ř	OFF	2004/09/22 13:19
516	2868440	reducing agent	US-PGPUB; USPAT; EPO; JPO; DERWENT	æ	OFF	2004/09/22 13:23

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Page 1

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2004/09/22 13:23	2004/09/22 13:34	2004/09/22 13:31	2004/09/22 13:31	2004/09/22 13:42
OFF	OFF.	0 <del>1</del>		<del>1</del>
Ж	SA S	8	S S	K
US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT
((("3-hydroxy-4-pyranes") or (hydroxy adj. butyrolactones) or borane borohydrides (dalkylamine adj boranes) formaldehyde (formic adj acid) hydrogen hydroquinones hydroxylamine (hypophosphorous adj acid) thydroxyberzene (sokated adj electrons) (sulfurous adj acid) and "451" clas.) and (reducing agent)	(451/41.ccls. and polish\$3) and pad	(451/56.cds. and polish\$3) and pad	(451/60.ccls. and polish\$3) and pad	(("3-hydroxy-4-pyrones") or (hydroxy adj1 butyrolactones) or borane borothydrides (dialkylamine adj boranes) formaldehyde (formic adj acid) hydrogen hydroquinones hydroxylamine (hypophosphorous adj acid) trihydroxybertzene (solvated adj electrons) (sulfurous adj acid) and (((451/41.cds. and polish\$3) and pad) or ((451/56.cds. and polish\$3) and pad) or ((451/56.cds. and polish\$3) and pad))
£8	1562	3%	263	337
SI7	S18	S19	S20	521

2004/09/22 13:35	2005/01/24 13:20	2004/09/22 13:38
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US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT
((("3-tydroxy-4-pyrones") or (hydroxy adj. butyrolactones) or borane borotydrides (dialkylamine adj boranes) formaldetyde (formic adj acid) hydrogen hydroquinones hydroxylamine (hypophosphorous adj acid) hydrogen hydroquinones hydroxylamine (hypophosphorous adj acid) and ((451/41.cds. and polish\$3) and pad) or ((451/56.cds. and polish\$3) and pad)) not ((451/41.cds. and polish\$3) and pad)) not ((451/41.cds. and polish\$3) and pad) or ((451/40.cds. and polish\$3) and pad) or ((451/40.cds. and polish\$3) and pad)) not (hydroxy adj. butyrolactones) or forane borohydrides (dialkylamine adj boranes) formaldehyde (formic adj acid) hydroxylentorene (sohvated adj electrons) (sulfurous adj acid) hydroxybenzene (sohvated adj electrons) (sulfurous adj acid) and (((451/40.cds. and polish\$3) and pad) or ((451/60.cds. and polish\$3) and pad)))))	((451/41.cds. and polish\$3) and pad) and ((("3+hydroxy-4-pyrones") or (hydroxy adj) tutyroladctones) or or hor and adj tutyroladramine adj boranes) formaldehyde (formic adj acid) hydrogen hydrocylniones hydroxylamine (hypophosphosphoross adj acid) tihydroxybenzene (solvated adj electrons) (sulfurous adj acid) tihydroxybenzene (solvated adj electrons) (sulfurous adj acid) and (((451/41.cds. and polish\$3) and pad) or ((451/60.cds. and polish\$3) and pad))))	(("3-hydnoxy-4-pynones") or (hydroxy adj. butynolactones) or borane borantyorides (dialikylamine adj boranes) formaldehyde (formic adj acid) hydrogen hydroquinones hydroxylamine (hypophosphorous adj acid) brindroxybenzene (sohvated adj electrons) (sulfurous adj acid) and (((451/56.cds. and polish\$3) and pad) or ((451/60.cds. and polish\$3) and pad)).
69	588	8
	ZZ .	225

2006/02/14 15:39	2004/09/22 14:22	2004/09/22 14:18	2004/09/22 14:19	2004/09/22 14:22	2004/09/22 14:23	2004/09/22 14:23	2005/01/21 15:29	2005/01/21 15:11	2005/01/21 15:12
OFF	FF0	PFI OFF	OFF	OFF.	OFF	OFF	OFF	PF0	OFF
OR.	8	R	æ	ଞ	æ	8	8	8	8
us-pgpub; uspat; epo; jpo; derwent	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	USPAT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT
(("3-hydroxy 4-pyrones") or (hydroxy adj.1 butyrolactones) or borane borolydrides (dialkylamine adj boranes) formaldehyde (formic adj acid) hydrogen hydroquinones hydroxylamine (hypophosphorous adj acid) trihydroxylearene (sokrated adj electrons) (sulfurous adj acid) ) and ((451/41.cds. and polish\$3) and pad)	oxidize\$4 and abrasive and polish\$4	oxidize\$2 and abrasive and polish\$4 and (reducing adj agent) and ((liquid or aqueous) adj carrier)	("4769046"   "5489233"   "6001269"   "5527423"   "5958794"   "6001269"   "6117000"   "6117000"   "6117000"   "6117000"   "6229795"   "2002/001732"   "2002/001732"   "2002/001732"   "2002/0017330"   "	tantalum	451/41.cds.	tantalum and 451/41.cds.	(\$1-alumina or alpha-alumina or (alpha near alumina)) with abrasive	"451.clas"	"451".das.
288	3038	-	12	77604	2905	190	895	0	64929
	9256	223	828	623	 සි	 83	 83	83	\$3 4

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#### **EAST Search History**

2005/01/21 16:01	2005/01/21 15:30	2005/01/21 15:30	2005/01/21 15:31	2005/01/21 16:01	2005/01/21 16:01	2005/01/21 16:01	2005/01/24 09:38	2005/01/24 10:45	2005/01/24 10:48	2005/01/24 09:58
OFF	OFF		- NF	OFF	OFF.	OFF		PF0	<b>T</b> F0	刊0
S)	Ř	R	ĸ	8	8	ĸ	R	8	g.	g S
US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	us-pgpub; uspat; epo; jpo; derwent	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT
S32 and S34	(silica or (fumed adj alumina)) with abrasive	(532 or 536) and 534	S35 and (reducing adj agent)	S37 and (reducing adj agent)	536 and 534	S40 and (reducing adj agent)	"6454822".pn.	"451".das.	S43 and (firdium adj oxide) or (tantalum same (oxidized, oxide, oxidizer))) and ((polishing adj pad or abrasive))	S43 and ((indium adj oxide) or (tantalum same (oxidized, oxide, oxidizer))) and ((polishing adj pad) or abrasive)
98	6947	. 1138	11	72	1109	24	2	64929	195	195
SS	ž	83	83	Š	8	<u>*</u>	84	8	*	25

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2005/01/24 09:59	2005/01/24 10:08	2005/01/24 11:17	2005/01/24 10:15	2005/01/24 10:15	2005/01/24 10:15	2005/01/24 10:15	2005/01/24 10:16	2005/01/24 10:16
OFF	OFF	OFF	OFF		OFF.	0FF	<b>140</b>	OFF
SO.	æ	R	æ	R	<b>&amp;</b>	80	8	8 S
US-PGPUB; USPAT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; -USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT				
(US-20020182982-\$ or US-20030013387-\$ or US-20040025495-\$ or US-2004013285-\$).did. or (US-6454822-\$ or US-6709316-\$). did.	S45 and S46	(silicone adj oxide) with "Si"	silicone near4 metal	silicone near2 metal	silicone near1 metal	S43 and S51	. S43 and S50	S43 and S49
v	2	37	6851	2852	740	H	Ŋ	=
₹	25	₹	<del>5</del>	220	251			

2005/01/24 10:17	2005/01/24 10:23	2005/01/24 10:24	2005/01/24 10:47	2005/01/24 10:46	2005/01/24 10:49	2005/01/24 10:49	2005/01/24 10:50	2005/01/24 11:17	2005/01/24 11:17
<del>L</del>	0FF	OFF	OFF	FIO	F0	94	9FF	OFF.	OFF
 క	SO.	g	В	ĸ	g	æ	g	g ,	g S
US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT
SS4 not SS1	SS4 not SS3	S47 and (indium adj oxide)	S43 and (iridium adj oxide)	"428",clas.	(substrate or wafer or semiconductor) with (indium adj oxide)	S43 and (indium adj oxide)	((substrate or wafer or semiconductor) with (indium adj oxide)) and ((polishing adj pad) or abrasive)	(copper adj oxide) with "Cu"	S63 and S43
01	9	0	2	212721	609	7	15	1388	<b>6</b>
SS	256		828	655	98	Se1	295	Seg	<b>%</b>

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OFF	FFO	OFF	-FF	OFF.	PFO	PF0	PF0	OFF	OFF	OFF
క	క	g	8	8	8	Ŗ.	8	æ	SO.	æ
US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT
(indium adj oxide) and (polish polishing CMP ("chemical mechanical polishing"))	S65 and (reducing adj agent)	(indium adj oxide) and (CMP ("chemical mechanical polishing"))	(indium adj oxide) and (CMP or ("chemical mechanical polishing"))	(indium adj oxide) same (CMP or ("chemical mechanical polishing"))	"4717581".pn.	"4679572",pn.	451/41.cds. and polish\$3	451/56.cds. and polish\$3	451/60.cds. and polish\$3	(S72 S73 S74) and ("pH" near2 (buffering buffer buffer\$4))
999	4	695	695	<del>,</del>	2	2	2567	. 550	427	8
S8.	98	282	98	695	220	172	272	573	S74	575

### **EAST Search History**

576 266 (\$72.573.5 577 1183 (ammonium ("ph" near buffer\$41) 578 366 (ammonium ("ph" near buffer\$41) 579 105 (ammonium ("ph" near buffer\$41)	(S72 S73 S74) and (surfactant)	US-PGPUB;	8	붠	2005/07/12 10:55
366		USPAT; USOCR; EPO; JPO; DERWENT			
366	(ammonium adj hydroxide) same "ph" near2 (buffering buffer buffer≄4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	ĕ	- OFF	2005/07/12 10:43
105	ammonium adj hydroxide) with "ph" near2 (buffering buffer buffer\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	8 S	OFF	2005/07/12 10:44
_	(ammonium adj hydroxide) near4 ("ph" near2 (buffering buffer buffer\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	S.	OFF	2005/07/12 10:44
S80 2 (572 573 S advantaged surfactant)	(S72 S73 S74) and ((advantages advantageous advantag55) with surfactant)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	S S	- OFF	2005/07/12 10:56
S81 5 ("451".dbs advantaged surfactant)	("451".das.) and ((advantages advantageous advantag\$5) with surfactant)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	æ	OFF	2005/07/12 11:00
S82 40 ("451".clas improved i surfactant)	("451".clas.) and ((desired improve improved improvement) with surfactant)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	S S	OFF	2005/07/12 11:05
S83 2 "5783489".pn.	°.pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	g S	OFF	2005/07/12 11:05

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2006/02/14 16:29

P.

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US-PGPUB; USPAT;

DERWENT

polishing" or "chemical mechanica

(polishing adj (pad pads)) and (CMP or "chemical mechanical

쫥

planarization") and ((reducing adj agent) with (hydroxylamine and

("3-hydroxy-4-pyrones") or

(hydroxy adj.1 butyrolactones) or borane or borohydrides or (dialkylamine adj borane\$3) or formaldehyde or (formic adj acid)

(hypophosphorous adj acid) or trihydroxybenzene or (solvated adj

electrons) or (sulfurous adj acid)))

(pod (sped bed) (be guiltiple)

**S85** 

(CMP or "chemical mechanical

or hydrogen or hydroquinone\$3 or

(hypophosphorous adj acid) or trihydroxybenzene or (solvated adj

or hydrogen or hydroquinone\$3 or

formaldehyde or (formic adj acid)

(dialkylamine adj borane\$3) or

borane or borohydrides or

(hydroxy adj1 butyrolactones) or

("3-hydroxy-4-pyrones") or

((reducing adj agent) with (hydroxylamine with

electrons) or (sulfurous adj acid))))

# **EAST Search History**

2006/02/14 16:56	2006/02/14 15:49	2006/02/14 15:49	2006/02/14 15:49
FF 0	F0	#O	490
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US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT
(CMP or "chemical mechanical polishing" or "chemical mechanical planarization") and (freducing adjagent) with (hydroxylamine and (fr3-hydroxy-4-pyrones") or (hydroxy adj! bukyneletnnes) or borane or borohydrides or (dalkylamine adj boranes3) or formaldehyde or (formic adjacid) or formaldehyde or (formic adjacid) or formaldehyde or (formic adjacid) or formolosphorous adjacid) or thydrophosphorous adjacid) or thydroxybenzene or (sohvated adjelectrons) or (sulfurous adjacid))))	(semiconductor wafer polish planaries substrate copper) and (l'educing adj agent) with (inydroxyamine and (l'3-hydroxy-4-pyrones") or (inydroxy adj 1 butyroleschoes) or borane or borankydrides or (dialkyfamine adj boraneş3) or formaldehyde or (formic adj acid) or hydrogen or hydroquinone\$3 or hydrogen or hydroquinone\$3 or hydrogen or hydroquinone\$3 or hydropen or kydrogen or hydroquinone\$3 or hydropen or hydroquinone\$3 or hydropen or kydrogen or hydroquinone\$3 or hydropen or kydrogen or kydroquinone\$3 or hydrogen or hydroquinone\$3 or hydroxybenzene or (solvated adj electrons) or (sulfurous adj acid))))	(wafer polish planarize substrate copper) and ((reducting adj agent) with (hydroxylamine and (("3-hydroxy-4-pyrones") or (hydroxy adj.1 butyrolactones) or borane or borohydrides or (dialkylamine adj borane\$3) or formaldehyde or (formic adj acid) or hydrogen or hydroquinone\$3 or (hypophosphorus adj acid) or hydrogen or hydroquinone\$3 or (hypophosphorus adj acid) or trihydroxyberzene or (sokrated adj electrons) or (sulfurous adj acid)))	(serniconductor polish planarize substrate copper) and ((reducing adj agent) with ((hydroxylamine and ((?3-hydroxy-4-pyrones²) or (hydroxy adj! butyrolactones) or borane or bronhydrides or (dialkylamine adj boraneş3) or formaldelyde or (formic adj add) or hydrogen or hydroquinone\$3 or (hypophosphrous adj add) or hydrogen or hydroquinone\$3 or tihydroxybenzene or (solvated adj electrons) or (suffurous adj acid)))
N	185	176	185
88	88	065	

2006/02/14 15:45

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trihydroxybenzene or (solvated adj electrons) or (sulfurous adj acid))))

or hydrogen or hydroquinone\$3 or (hypophosphorous adj acid) or

US-PGPUB; USPAT; EPO; JPO; DERWENT

(hydroxylamine with (("3-hydroxy-4-pyrones") or (hydroxy adj1 butyrolactones) or

((reducing adj agent) with

241

88

(dialkylamine adj borane\$3) or formaldehyde or (formic adj acid) or hydrogen or hydroquinone\$3 or

borane or borohydrides or

trihydroxybenzene or (solvated adj electrons) or (sulfurous adj acid))))

(polishing adj (pad pads)) and

88

(hypophosphorous adj acid) or

2006/02/14 15:45

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US-PGPUB; USPAT; EPO; JPO; DERWENT

2006/02/14 15:44

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US-PGPUB; USPAT; EPO; JPO; DERWENT

polishing" or "chemical mechanical

planarization") and ((reducing ad)

agent) with (hydroxylamine with

(("3-hydroxy-4-pyrones") or

(hydroxy adj.1 bukrolactones) or borane or borohydrides or (dialkylamine adj borane\$3) or formaldehyde or (formic adj acid)

2006/02/14 15:49	2006/02/14 15:56	2006/02/14 15:50	2006/02/14 15:50
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US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT
(semiconductor planarize substrate copper) and ((reducing adi agent) with (hydroxylamine and (('3-hydroxy-4-pyrones') or (hydroxy adi) tuthrolactones) or charactor browhydrides or (dalkykamine adi boranes'3) or formaldehyde or (formic adi acid) or hydrogen or hydroquinones'3 or hydrogen or hydroquinones'3 or hydropen or hydroquinones'3 or hydroxybenzene or (solvated adi electrons) or (sulfurous adi acid))))	(semiconductor substrate copper) and ((reducing adj agent) with thydroxylamine and ((13-hydroxy4-pyrones") or ((13-hydroxy4-pyrones") or (hydroxy adj.1 butyrolactones) or conen or borohydrides or (dialkylamine adj borane\$3) or formaldehyde or (formic adj acid) or hydrogen or hydroquinone\$3 or (hypophosphorous adj acid) or thydroxybenzene or (solvated adj electrons) or (sulfurous adj acid))))	(semiconductor copper) and (reducing adj agent) with (hydroxylamine and (("3-hydroxy 4-pyrones") or (hydroxy adj! butyrolactones) or borane or borohydrides or (dialkylamine adj borane\$\$\frac{1}{2}\$\text{or}\$ or formaldehyde or (formic adj acid) or hydrogen or hydroquinone\$\$\frac{1}{2}\$\text{or}\$ or hydroquinone\$\$\frac{1}{2}\$\text{or}\$ or hydroquinone\$\$\frac{1}{2}\$\text{or}\$ or hydroquinone\$\$\frac{1}{2}\$\text{or}\$ or hydroquinone\$\$\frac{1}{2}\$\text{or}\$ inhydroxybenzene or (solvatted adj electrons) or (sulfurous adj acid)))	(semiconductor substrate ) and (freducing adj agent) with (hydroxylamine and ("3-hydroxy adj! butyrolactones") or borane or borohydrides or (hydroxy adj! butyrolactones) or borane or borohydrides or (dialkylamine adj borane\$3) or formaldehyde or (formic adj acid) or hydrogen or hydroquinone\$3 or hydrogen or hydroquinone\$3 or hydroxybencus adj acid) or hydroxybenzene or (solvated adj electrons) or (sulfurous adj acid))))
185	185	153	4
283	283	488	295

#### **EAST Search History**

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US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	US-PGPUB; USPAT; EPO; JPO; DERWENT	
(semiconductor semiconductors) and ((reducing adj agent) with (hydroxylamine and "("3-hydroxy4-pyrones") or (hydroxy adj1 butyrolactones) or borane or borohydrides or (dialkylamine adj borane\$3) or (dialkylamine adj borane\$3) or hydrogen or hydrogen or hydrogen or hydrogen or hydrogen or hydrogen adj acid) or hydrogen or hydrogen adj acid) acid) acid) acid, acid	trihydroxyberzene or (solvated adj electrons) or (sulfurous adj acid)))) (("451".clas.) or ("428".clas.) or ("51".clas.)) and ((reducing adj agent) with (hydroxylamine and ("3-hydroxy 4-pyrones") or (hydroxy adj1 butyrolectones) or borane or bonohydrides or (dialkylamine adj borane\$3) or formaldehyde or (formic adj acid)	or hydrogen or hydroquinoness or of hydrogen or hydroquinoness or or trihydroxyberasen or (solvated adjectrons) or (sulfurous adj acid)))) ((polishing adj (pad pads)) or (CMP or "chemical mechanical polishing" or "chemical mechanical apharatration")) and ((reducing adjaparatration")) and ((reducing adjaparatrationxy adj1 butyrolasy) or (hydroxy adj1 butyrolastones) or	borane or borohydrides or (dialkylamine adj boranes) or formaldelyde or (formic adj acid) or hydrogen or hydroquinones3 or (hypophrosphorus adj acid) or trihydroxybenzene or (solvated adj electrons) or (sulfurous adj acid))) ((polishing adj (pad pads)) or (CMP or "chemical mechanical polishing" or "chemical mechanical polishing" or "chemical mechanical polishing or "chemical mechanical polishing" or "chemical solution) and ((reducing adj agent) with	(('3-hydroxy-4-pyrones'') or (hydroxy adl) tutyrolectones) or borane or borohydrides or (dialkylamine adj borane\$3) or formaldehyde or (formic adj acid) or hydrogen or hydroquinone\$3 or (hypophosphorous adj acid) or trihydroxybenzene or (sohated adj electrons) or (sulfurous adj acid)))
62	π	345	308	
<b>96</b> S	283	S98	66S	

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((polishing adj (pad pads)) or (CMP to "chemical mechanical polishing" to "chemical mechanical planarization")) and (slurry composition) and (treducing adj agent) with

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3 3	4	(CMP or "chemical mechanical polishing" or "chemical mechanical planarization") and ((reducing adjagent) with (hydroxy4-pyrones") or (hydroxy4-pyrones") or (hydroxy4-pyrones") or channe or boronhydrides or or borone or boronhydrides or (dally/amine adj borane\$3 or formaldehyde or (formic adjacid) or hydrogen or hydroquinone\$3 or hydroquinones\$3 or hydrogen o	US-PGPUB; USPAT; EPO; JPO; DERWENT	Ŗ	HO PH	2006/02/14 17:17
8 to 10 to 1	0	(CMP or "chemical mechanical polishing" or "chemical mechanical planarization" and (freducing adjagent) with (glucose sulfothionate (potassium adj iodidel) with ("3-hydroxy-4-pyrones") or (hydroxy adj.1 butynolactones) or borane or borohydrides or (formic adjacid) or formaldehyde or (formic adjacid) or hydroguinone\$3 or flypophosphorous adjacid) or hydroguinone\$3 or hyd	US-PGPUB; USPAT; EPO; JPO; DERWENT	К	F10	2006/02/14 16:57
5 5	94	((polishing adj (pad pads)) or planarize planarization slurry) and ((reducing adj agent) with ((glucose sulfothiorate (potassium adj iodide)) with (("3-hydroxy-4-pyrones") or (hydroxy-4-pyrones") or hydroxy-4-pyrones) or borane or borohydrides or (hydroxy-4-pyrones) or formaldehyde or (formic adj acid) or formaldehyde or (formic adj acid) or hydrogen or hydroquinone\$3 or flypophosphorous adj acid) or hydrogen or hydroquinone\$3 or hydrogen or hydroguinone\$3 or hydrogen or hydroguinone\$3 or hydrogen or hydroguinone\$3 or hydrogen or hydroguinone\$3 or hydrogen or solvated adj electrons) or (sulfurous adj acid))))	US-PGPUB; USPAT; EPO; JPO; DERWENT	A.	PF0	2006/02/14 17:01

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((polishing adj (pad pads)) or (CMP or "chemical mechanical polishing" or "chemical mechanical

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S10 1

planarization")) and ((reducing adj

or hydrogen or hydroquinone\$3 or (hypophosphorous adj acid) or trihydroxybenzene or (solvated adj electrons) or (sulfurous adj acid)))

formaldehyde or (formic adj acid)

(hydroxy adj1 butyrolactones) or borane or borohydrides or (dialkylamine adj borane\$3) or

(("3-hydroxy-4-pyrones") or

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US-PGPUB;

(hypophosphorous adj acid) or trihydroxybenzene or (solvated adj electrons) or (sulfurous adj acid)))

(dialkylamine adj borane\$3) or formaldehyde or (formic adj acid)

or hydroguinone\$3 or

(hydroxy adj1 butyrolactones) or borane or borohydrides or

("3-hydroxy-4-pyrones") or

agent) with

USPAT; EPO; JPO; DERWENT

polishing" or "chemical mechanical planarization") and ((reducing adjagent) with ((hydroxylamine

(CMP or "chemical mechanical

S10

glucose sulfothionate (potassium

adj iodide)) with (("3-hydroxy-4-pyrones") or (hydroxy adj1 butyrolactones) or borane or borohydrides or

or hydrogen or hydroquinone\$3 or (hypophosphorous adj acid) or brihydroxybenzene or (solvated adj electrons) or (sulfurous adj acid))))

formaldehyde or (formic adj acid)

(dialkylamine adj borane\$3) or

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**EAST Search History** 

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#### 2006/02/14 17:49 2006/02/14 17:53 2006/02/15 08:55 2007/03/15 15:43 2006/02/15 09:28 2006/02/15 09:28 2007/03/15 12:06 ᆼ Ŗ 유 Ŗ H R F 8 క ర క క 8 ଞ US-PGPUB; USPAT; EPO; JPO; DERWENT US-PGPUB; US-PGPUB; US-PGPUB; USOCR; EPO; JPO; DERWENT US-PGPUB; US-PGPUB; US-PGPUB; USPAT; EPO; JPO; DERWENT USOCR; EPO; JPO; DERWENT USOCR; EPO; JPO; DERWENT USOCR; EPO; JPO; DERWENT USOCR; EPO; JPO; DERWENT USPAT; USPAT; USPAT; "|"5527423"|"5691219"|"5958794"| "6117783"|"6139763"|"6274063"|"6 313039"|"6315803"|"6419554"|"652 planarization") and (hydroxylamine with (("3-hydroxy-4-pyrones") or (hypophosphorous adj acid) or trihydroxybenzene or (solvated adj electrons) or (sulfurous adj acid))) 2.1..02806002002..1..65865002002..) 0013387"|"20030119319"|"5489233 adj acid) same ((dimethylamine adj (CMP or "chemical mechanical polishing" or "chemical mechanical (dialkylamine adj borane\$3) or formaldehyde or (formic adj acid) mechanical planarization").ti.) and ((reducing adj agent) same (oxalic (hydroxy adj1 butyrolactones) or borane or borohydrides or mechanical polishing" "chemical 0020102923"|"20020111027"| (complexing adj agent) with (chelating adj agent) "hydroquinone sulfonic acid" ((polishing cmp "chemical "hypophosphorous acid" trihydroxybenze\$4)) borane) hydroquinone or hydroquinone\$3 or 10/753138.app. 09/755717.app. S107 not S109 7622").PN. 74 31 32 339 S11 S11 0 S11 S11 S11 S11 5 S11 6

Page 17

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	mechanical polishing" "dhemical mechanical palaarization") and ((reducing adi agent) same (oxalic adi acid) same ((dimethylamine adi borane) hydroquinone sulfonic acid" "hypophosphorous acid" trihydroxybenze\$41))	(polishing cmp "dhemical mechanical polishing" "dhemical mechanical planarization") and ((reducing adj agent) same (ozalic adj acid) same ((dimethylamine adj borane) hydroquinone sulfonic acid" "hydroquinone sulfonic acid" trihydroxybenze\$4) hydrogen borane borohydride\$4 "sulfurous acid")	((polishing cmp "dhemical mechanical polishing" "dhemical mechanical phararization"), it.) and ((reducing adj agent) same (osalic adj acid) same ((dimethylamine adj acid) same (idimethylamine adj acid) same (idimethylamine adj acid) same (idimethylamine adj acid) same (idimethylamine adj acid) shypophosphorous acid" hypophosphorous acid" trihydnoybenze\$4 hydrogen borane borohydride\$4 "sulfurous acid"))	((polishing cmp "chemical mechanical polishing" "chemical mechanical planarization"), it.) and ((reducing adj agent) same ((oxalic adj adol) formaldebyde (formic adj acid)) same ((dimethydamine adj borane) hydroquinone sulfonic acid" "hydroquinone sulfonic acid" "hypophosphorous acid" trihydroxybenze\$4))	("451".clas.) and ((reducing adj. agent) same ((oxalic adj acid)) formaldehyde (formic adj acid)) same ((dimethylamine adj borane) hydroquinone "hydroquinone sulfonic acid" "hypophosphorous acid" trihydroxybenze\$41)
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\$11		8 8	9	S12 0	S12 1

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2007/03/16 13:16	2007/03/15 12:55	2007/03/15 12:54	2007/03/15 12:55	2007/03/15 13:14	2007/03/15 12:55	2007/03/15 13:16	2007/03/15 13:15	2007/03/15 13:16	2007/03/15 13:17
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((reducing adj agent) same ((oxalic adj acid) formaldetyde (formic adj acid)) same ((dimetrylamine adj borane) hydroquinone "hydroquinone sulfonic acid" "hypophosphorous acid" trihydroxybenze\$4))	((polishing adj (pad pads)) or (CMP or "chemical mechanical polishing" or "chemical mechanical planarization") semiconductor (oxidize\$4 near3 metal) slumy)	((polishing adj (pad pads composition compositions)) or (CMP or "chemical mechanical polishing" or "chemical mechanical planarization") semiconductor (oxidize\$4 near3 metal) slurry)	S122 and S124	((polishing adj (pad pads)) or (CMP or "chemical mechanical or "chemical mechanical planarization") semiconductor stury)	S122 and S126	((polishing adj (pad pads)) or (CMP or "chemical mechanical polishing" or "chemical mechanical planarization") semiconductor)	(reducing adj agent) same ((oxalic adj acid) formaldehyde (formic adj acid))	S128 and S129	((polishing adj (pad pads)) or (CMP or "chemical mechanical polishing" or "chemical mechanical planarization") semiconductor), ti.
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S131 and S129	(polishing cmp "chemical mechanical polishing" "chemical mechanical planarization") and mechanical planarization") and ((reducing adj agent) same (oxalic adj acid) same (idimethylamine adj borane) hydroquinone sulfonic acid" "hypophosphoric acid" trihydroxybenze\$41))	(polishing cmp "chemical mechanical polishing" "chemical mechanical pulshing" "chemical mechanical planarization") and ((reducing adj agent) same (osalic adj acid) same ((dimethylamine adj porane) hydroquinone "hydroquinone sulfonic acid" "hyprophosphorus acid" trihydroxybenze\$41).	((polishing cmp "chemical mechanical polishing" "chemical mechanical planarization"). It,) and ((oxalic adj acid\$3) formaldehyde (formic adj acid\$3) same ((dimethylam\$4 adj borane\$4) hydroquinone "hydroquinone sulfonic acid" (hypophosphorava adj acid\$3) (hydroxybenze\$4) acid\$3) (hydroxybenze\$4) acid\$3) inhydroxybenze\$4	(reducing adj agent) and ((oxalic adj acid\$3) formaldehyde (formic adj acid\$3)) same ((dimethylam\$4 adj borane\$4) hydroquinon\$4 "hydroquinone sulfonic acid" (hypophosphorous adj acid\$3) (hydrophosphor\$4) trihydroxybenze\$4)	(polishing cmp "chemical mechanical polishing" "chemical mechanical planarization")	S136 and S137
88	4	м		937	249916	71
S13 2	33	4 4	52.	513	S13 7	S13 8

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2007/03/15 15:05		2007/03/15 15:06	2007/03/15 15:06	2007/03/16 08:40	2007/03/15 15:07	2007/03/15 15:34	2007/03/15 15:43	2007/03/15 16:08
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US-PGPUB;	USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT
(cmp "chemical mechanical	polishing" "chemical mechanical planarization")	S136 and S138	S136 and S139	S136 and tantalum	S142 and S141	((reducing adj agent) reductant reduc\$4) and ((oxalic adj acid\$3) formalder/yde (formic adj acid\$3)) same ((dimethylam\$4 adj borane\$4) hydroquinon\$4 hydroquinone sulfonic acid" (hypophosphoraus adj acid\$3) (hydrophosphor\$4 adj acid\$4) trihydroxybenze\$4)	S136 and tantalum and redox	((polishing cmp "chemical mechanical polishing" "chemical mechanical polishing" "chemical mechanical planarization")) and ((oxalic adj acid\$3) some ((formic adj acid\$3)) same ((dimethylam\$4 adj borane\$4) hydroquinone "hydroquinone "hydroquinone acid\$3) (hydrophosphor\$4 adj acid\$3) (hydrophosphor\$4 adj acid\$3) trihydroxyberze\$4)
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US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	US-PGPUB; USPAT; USOCR;
(reducing adj agent) and ((oxalic adj acid\$3) formaldehyde (formic adj acid\$3)) same ((dimethylam\$4 adj borane\$4) hydroquinon\$4 hydroquinons sulfonic acid" (hypophosphorst adj acid\$3) (hydrophosphor\$4 adj acid\$4) trihydroxybenze\$4)	S152 and (tantalum adj oxide)	S152 and (tantalum adj oxide) and (iridium ruthenium platinum thodium palladium silver osmium gold)	S152 and (tantalum adj oxide) and ((tridium ruthenium platinum rhodium palladium silver osmium gold) near2 oxide)	S152 and (tantalum adj oxide) and ((indium ) near2 oxide)	(donatst near3 electronst4) same ((oxalic adj acids3) formaldehyde (formic adj acids3)) same ((dimethylamst adj boranest) hydroquinonst "hydroquinone sulfonic acid" (hypophosphorous adj acids1) (hydrophosphorst adj acids1) trihydroxybenzest4)	(reducing adj agent) same ((oxalic adj acid) same ((dimethylamine adj borane) hydroquinone "hydroquinone sulfonic acid" "hypophrosphorous acid" trihydroxybenze\$4))	((known common typical) near3 (reducing adj agent\$3)) same ((oxalic adj acid) same
937	13		ω	7	4	28	4
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Page 23

Page 24

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(US-20020086511.\$ or US-20020017063.\$ or US-20020042208.\$ or US-20020042208.\$ or US-20020182982.\$ or US-200402945.\$ or US-200402945.\$ or US-200402945.\$ or US-2004029405.\$ or US-200402495.\$ or US-2003013387.\$ or US-200301378.\$ or US-20030107465.\$ or US-20030107465.\$ or US-20030107465.\$ or US-20030107465.\$ or US-20030107465.\$ or US-20030107465.\$ or US-6756308.\$ or US-5683443.\$ or US-6756308.\$ or US-5683443.\$ or US-6709316.\$ or US-6339763.\$ or	"23" and acsorbic	S160 and acsorbic	((polishing cmp "chemical mechanical polishing," "chemical mechanical planarization").(It.) and ((reducing adj agent) same (ascorbic))	((polishing cmp "chemical mechanical polishing," "chemical mechanical planarization").ti.) and (ascorbic)	((polishing cmp "chemical mechanical polishing!" "chemical mechanical planarization"). it.) and ((accorbic) same (formic formaldehyde))	09/384946.app.	((polishing cmp "chemical mechanical polishing" "chemical mechanical planarization").tl.) and ((ascorbic) same reducing)
B	Ω.	0	^		20	<b>-</b>	33
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7	10/901420.app.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	S S	OFF	2007/06/27 11:40
4	("20010048161"   "20020017063"   "2002003839"   "20020056701"   "20020058291"   "20020056829"   "20020058291"   "20020058291"   "20020016937"   "20020016937"   "20020110327"   "2002011037"   "2002011334"   "20020111027"   "20030134184"   "20030124897"   "20030124897"   "20030124897"   "20030124897"   "20030124897"   "2003012487"   "2003012487"   "2003012487"   "2003012497"   "2003012497"   "2003012497"   "2003012497"   "2003012497"   "2003012497"   "2003012497"   "2003012497"   "6641957"   "6537628"   "6537628"   "6537628"   "6537628"   "6537628"   "6537628"   "6537628"   "6537628"   "6537628"   "6537628"   "6537628"   "6537628"   "6537628"   "6537628"   "6537628"   "6668239"   "6641957"   "6641957"   "6641957"   "66605339"   "6641630"   "6641630"   "6604987"   "665239"   URPN.	USPGPUB; USPAT; USOCR	٥	946 	2007/06/27 11:41
8	S170 and ascorbic	US-PGPUB; USPAT; USOCR	e e	OFF	2007/06/27 13:09
	(polish\$4 and metal and oxid\$4 and ascorbic and abrad\$4).clm.	US-PGPUB; USPAT; USOCR	К	OFF	2007/06/27 13:09